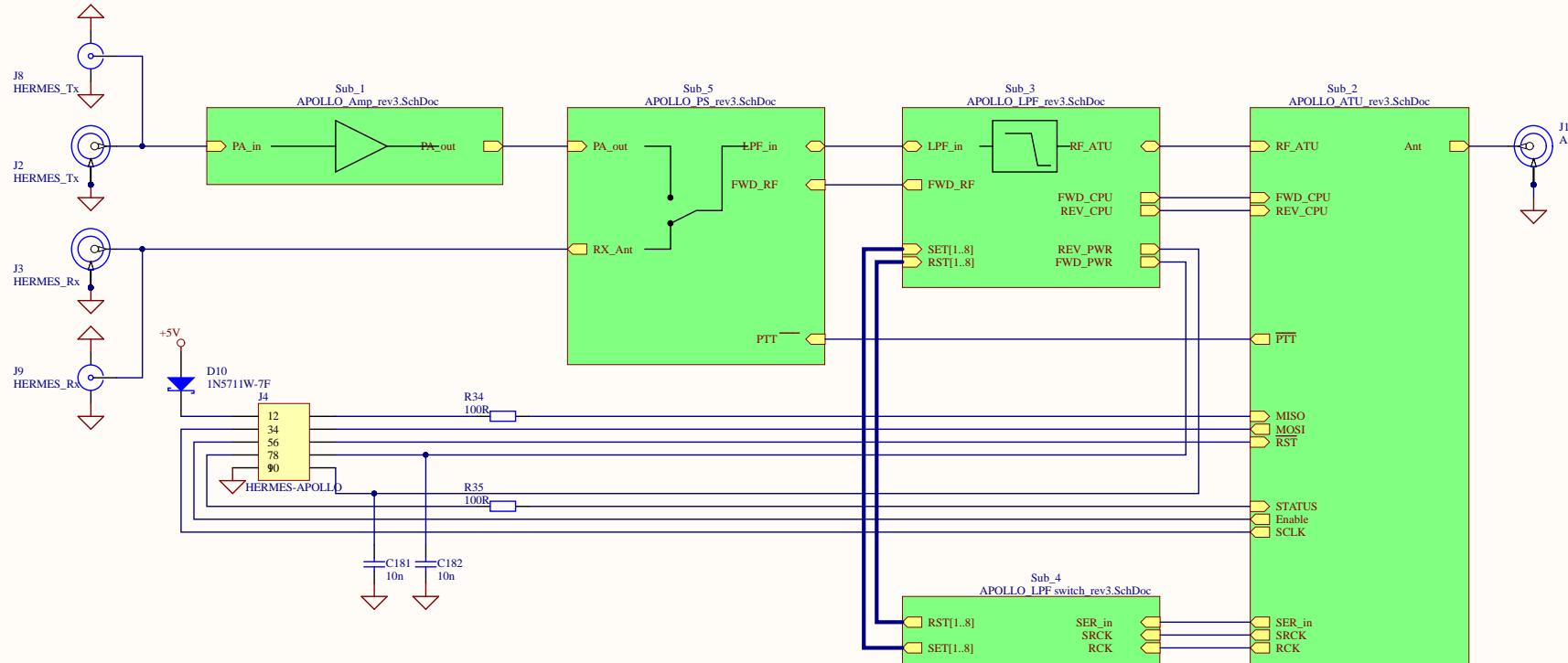
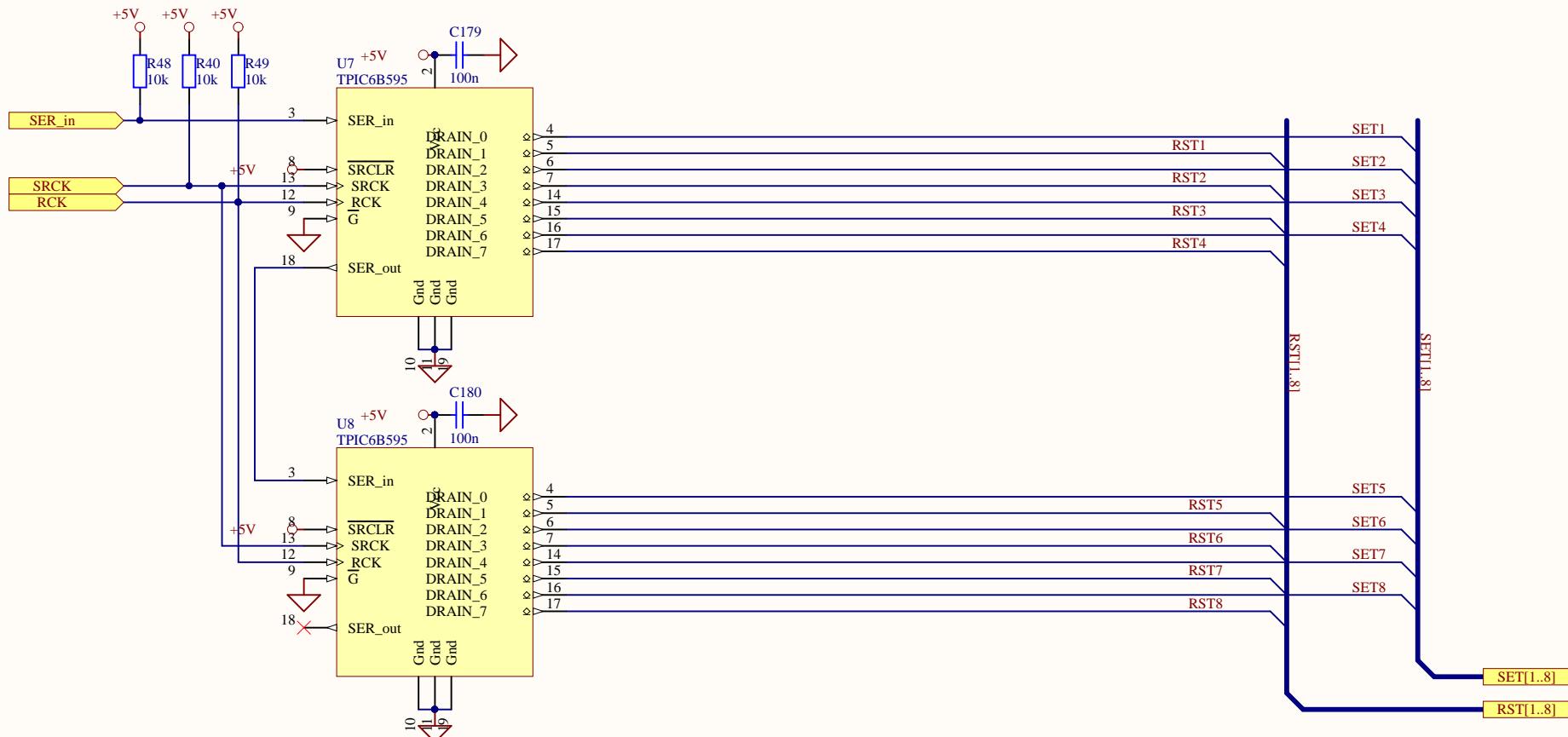


MP1
 ▶ FIDucial1
 MP2
 ▶ FIDucial2
 MP3
 ▶ FIDucial3
 MP4
 ▶ FIDucial4
 MP5



A

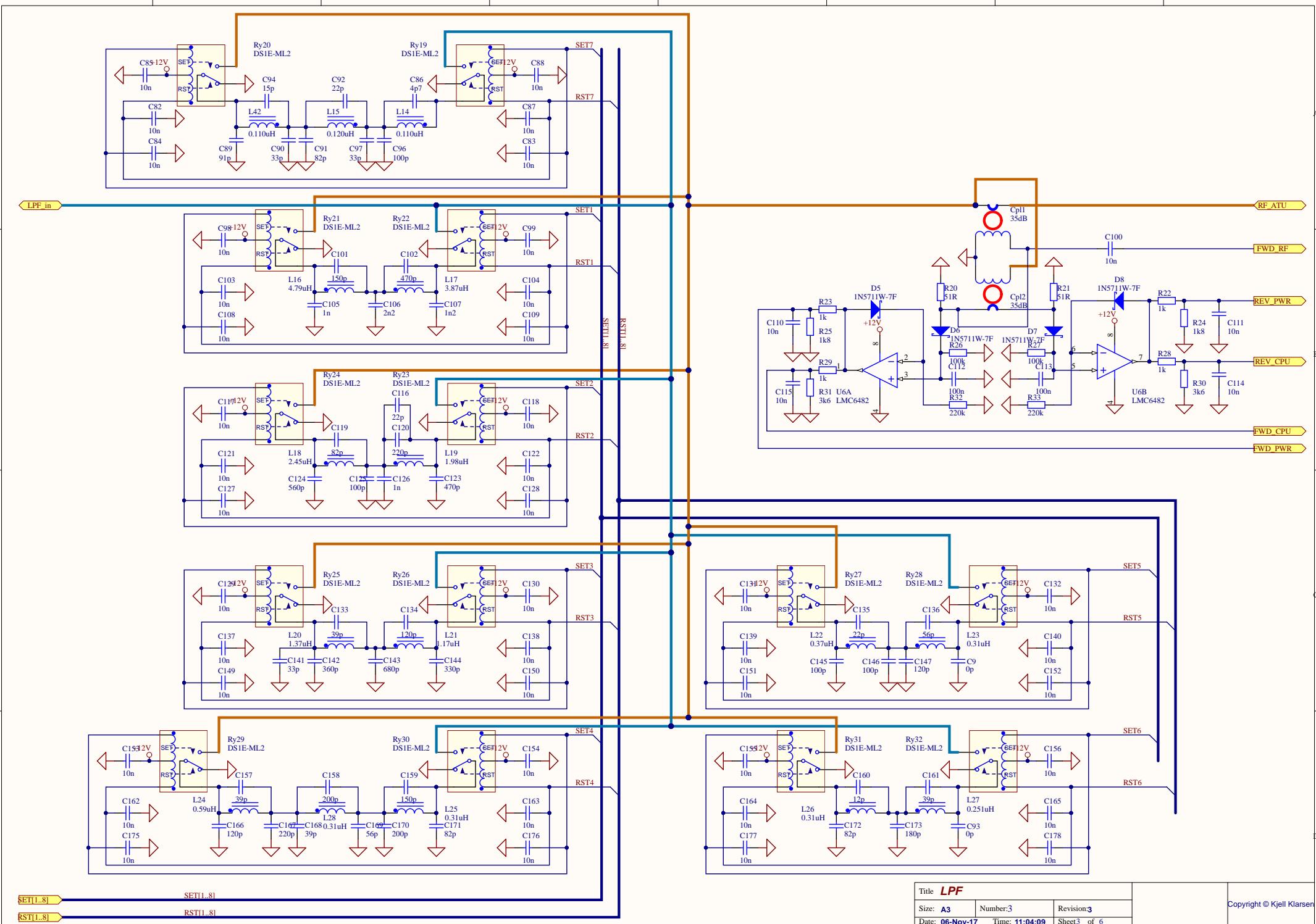
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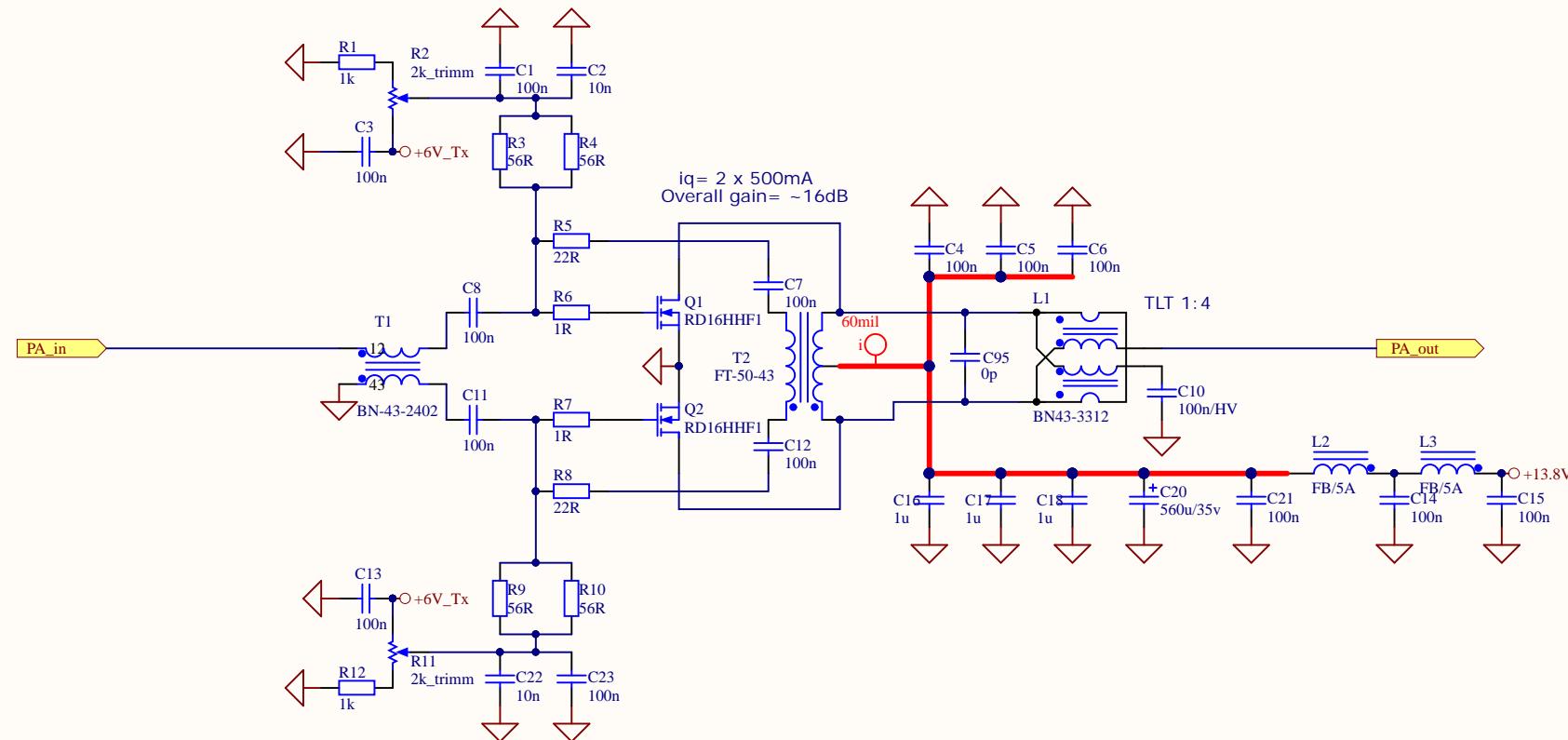
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Date: 06-Nov-17 Time: 11:04:09 Sheet 2 of 6

File: D:\Dropbox\QRP CLUB\HPSDR_APOLLO\HW_rev3\APOLLO_LPF switch_rev3.SchDoc

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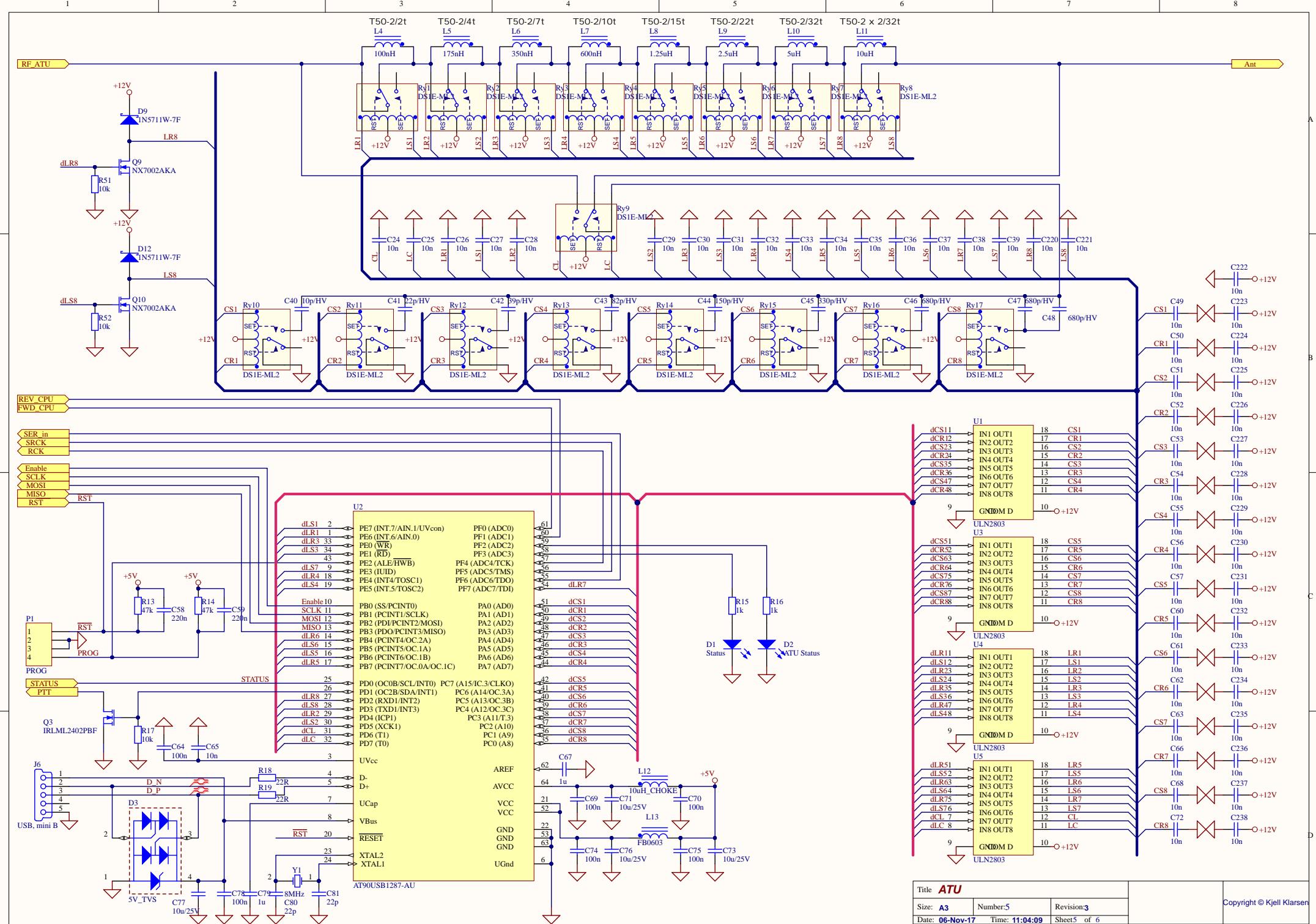
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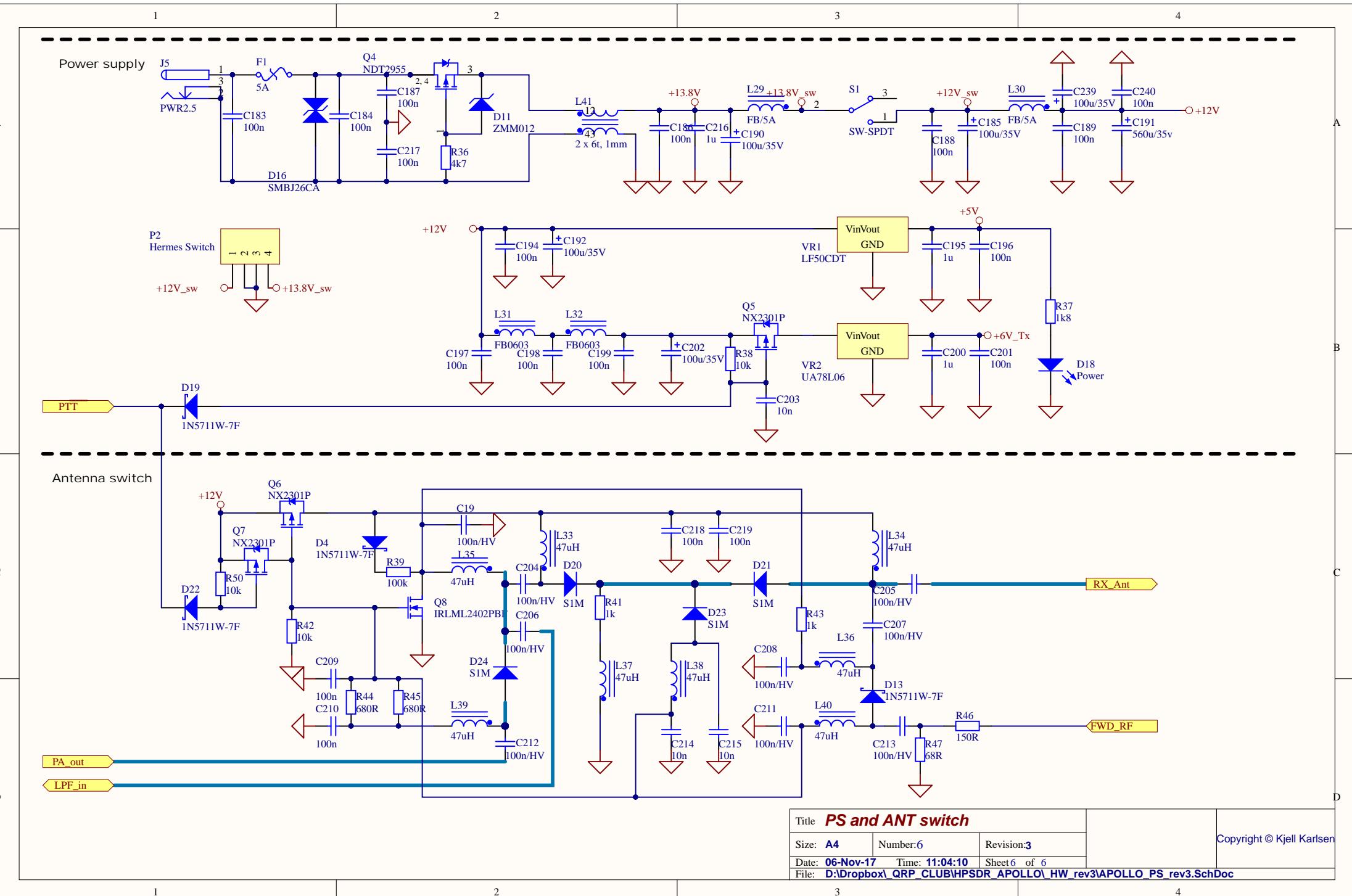
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Date: 06-Nov-17 Time: 11:04:09 Sheet 4 of 6

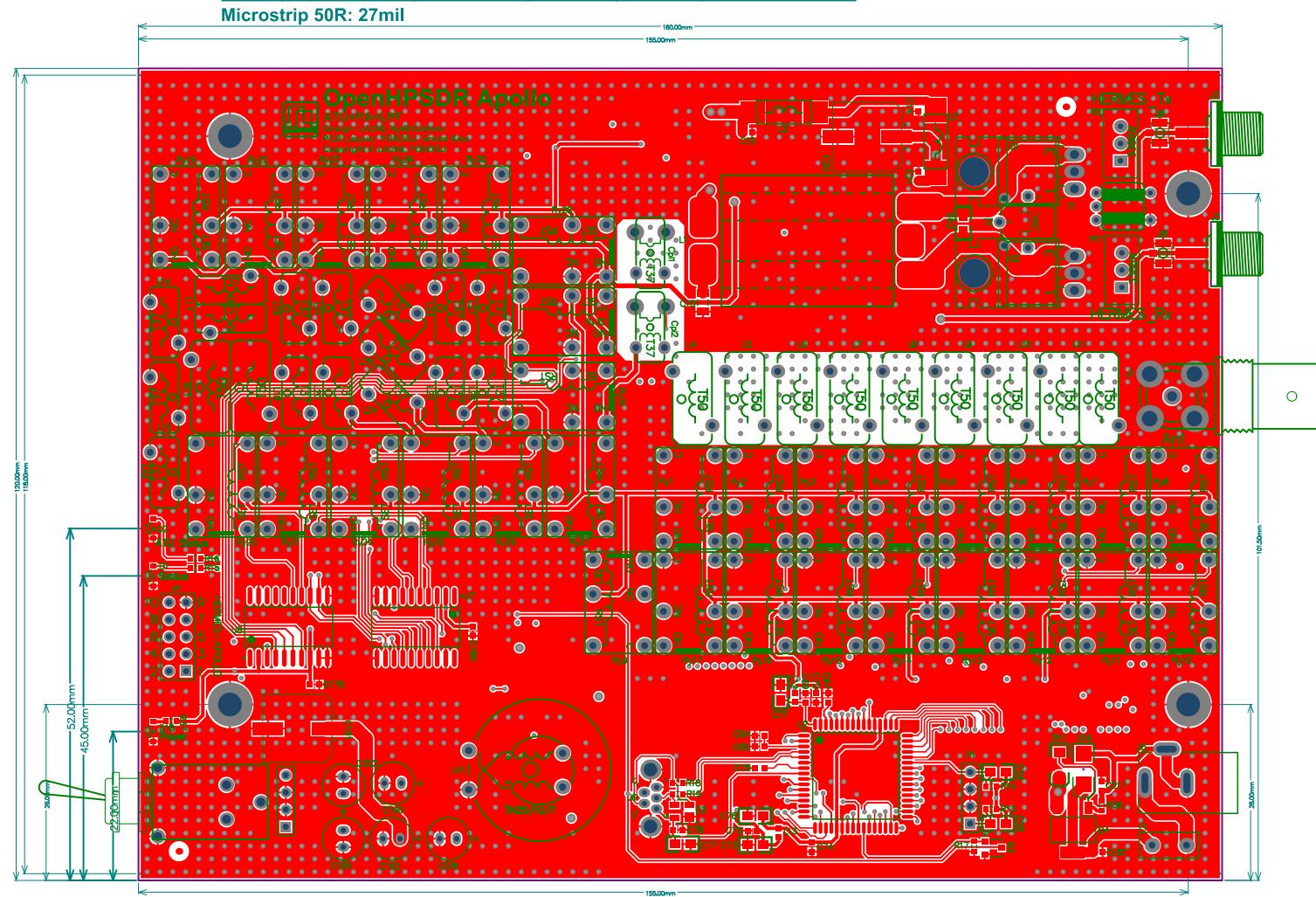
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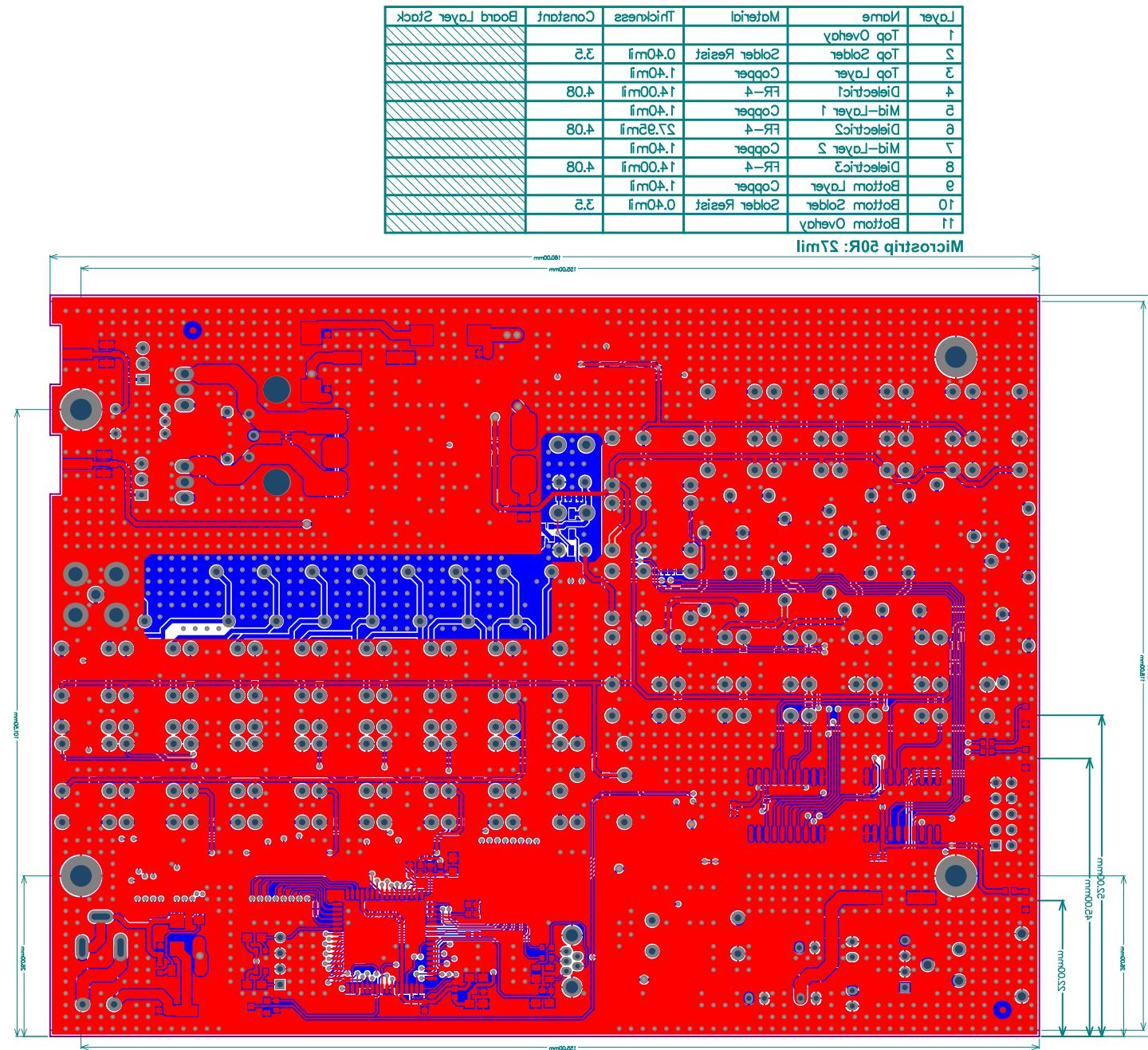
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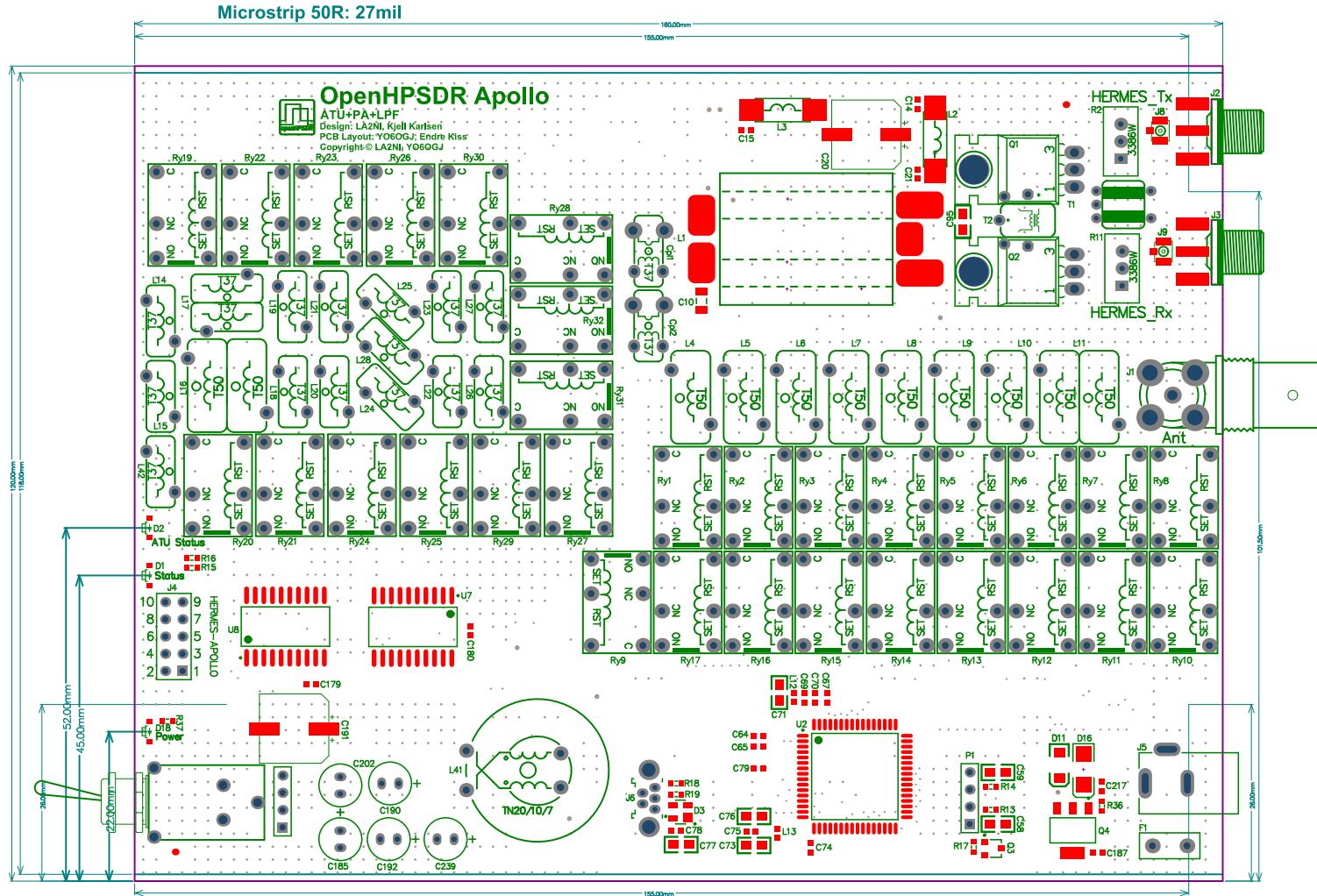


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	14.00mil	4.08	
5	Mid-Layer 1	Copper	1.40mil		
6	Dielectric2	FR-4	27.95mil	4.08	
7	Mid-Layer 2	Copper	1.40mil		
8	Dielectric3	FR-4	14.00mil	4.08	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				





Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	14.00mil	4.08	
5	Mid-Layer 1	Copper	1.40mil		
6	Dielectric2	FR-4	27.95mil	4.08	
7	Mid-Layer 2	Copper	1.40mil		
8	Dielectric3	FR-4	14.00mil	4.08	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



Layer	Name	Material	Thickness	Count/Unit	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40μm	35	
3	Top Layer	Copper	1.40μm	408	
4	Dielectric1	FR-4	1.40μm	408	
5	Mid-Layer 1	Copper	1.40μm	408	
6	Dielectric2	FR-4	1.73μm	408	
7	Mid-Layer 2	Copper	1.40μm	408	
8	Dielectric3	FR-4	1.40μm	408	
9	Bottom Layer	Copper	1.40μm	408	
10	Bottom Solder	Solder Resist	0.40μm	35	
11	Bottom Overlay				

